



64-Lane 16-Port PCI Express® System Interconnect Switch

89HPES64H16 Product Brief Preliminary Information*

Device Overview

The 89HPES64H16 is a member of the IDT PRECISE™ family of PCI Express® switching solutions. The PES64H16 is a 64-lane, 16-port system interconnect switch optimized for PCI Express packet switching in high-performance applications, supporting multiple simultaneous peer-to-peer traffic flows. Target applications include servers, storage, communications, and embedded systems.

Utilizing standard PCI Express interconnect, the PES64H16 provides the most efficient system interconnect switching for applications requiring high throughput, low latency, and simple board layout with a minimum number of board layers. It provides 256 Gbps of aggregated, full-duplex switching capacity through 64 integrated serial lanes, using proven and robust IDT technology. Each lane provides 2.5 Gbps of bandwidth in both directions and is fully compliant with PCI Express Base specification 1.1.

The PES64H16 is based on a flexible and efficient layered architecture. The PCI Express layer consists of SerDes, Physical, Data Link and Transaction layers. The PES64H16 can operate either as a store and forward switch or a cut-through switch and is designed to switch memory and I/O transactions. It supports eight Traffic Classes (TCs) and two Virtual Channels (VC) with sophisticated resource management to enable efficient switching and I/O connectivity.

Features

♦ High Performance PCI Express Switch

- Sixteen maximum switch ports
 - Eight main ports each of which consists of 8 SerDes
 - Each x8 main port can further bifurcate to 2 x4-ports
- Sixty-four 2.5 Gbps embedded SerDes
 - Supports pre-emphasis and receive equalization on per-port basis
- Delivers 256 Gbps (32 GBps) of aggregate switching capacity
- Low-latency cut-through switch architecture
- Support for Max Payload Size up to 2048 bytes
- Supports two virtual channels and eight traffic classes
- PCI Express Base Specification Revision 1.1 compliant

♦ Flexible Architecture with Numerous Configuration Options

- Port arbitration schemes utilizing round robin or weighted round robin algorithms
- Virtual channels arbitration based on priority
- Automatic per port link width negotiation to x8, x4, x2 or x1
- Automatic lane reversal on all ports
- Automatic polarity inversion on all lanes
- Supports locked transactions, allowing use with legacy software

- Ability to load device configuration from serial EEPROM
- Ability to control device via SMBus
- ♦ **Highly Integrated Solution**
 - Requires no external components
 - Incorporates on-chip internal memory for packet buffering and queueing
 - Integrates sixty-four 2.5 Gbps embedded full duplex SerDes, 8B/10B encoder/decoder (no separate transceivers needed)
- ♦ **Reliability, Availability, and Serviceability (RAS) Features**
 - Redundant upstream port failover capability
 - Supports optional PCI Express end-to-end CRC checking
 - Internal end-to-end parity protection on all TLPs ensures data integrity even in systems that do not implement end-to-end CRC (ECRC)
 - Supports optional PCI Express Advanced Error Reporting
 - Supports PCI Express Hot-Plug
 - Compatible with Hot-Plug I/O expanders used on PC motherboards
 - Supports Hot-Swap
- ♦ **Power Management**
 - Supports PCI Power Management Interface specification, Revision 1.1 (PCI-PM)
 - Supports powerdown modes at the link level (L0, L0s, L1, L2/L3 Ready and L3) and at the device level (D0, D3_{hot})
 - Unused SerDes disabled
- ♦ **Testability and Debug Features**
 - Built in SerDes Pseudo-Random Bit Stream (PRBS) generator
 - Ability to read and write any internal register via the SMBus
 - Ability to bypass link training and force any link into any mode
 - Provides statistics and performance counters
- ♦ **Thirty-two General Purpose Input/Output pins**
 - Each pin may be individually configured as an input or output
 - Each pin may be individually configured as an interrupt input
 - Some pins have selectable alternate functions
- ♦ **Packaged in a 35mm x 35mm 1156-ball Flip Chip BGA with 1mm ball spacing**

Block Diagram

